

- ⊗ Wavelength: 735+/-5 nm
- ⊗ Output Power: Up to 1750mW free space / 1400mW fiber coupled
- ⊗ High output power and high efficiency
- ⊗ Proven reliability
- ⊗ Custom packaging available
- ⊗ Custom wavelengths and laser designs are available.



The LDX-3110-735 is a high-power laser diode chip. Designed for low divergence and high brightness, and offers proven reliability. This chip is used in a wide range of applications in the medical, industrial, research, and military markets.

These lasers are available in the following free space and fiber-coupled packages:

C-mount, B-mount, COS, 9mm, 9mm Isolated, 9mm Special, TO3, TO3-TEC, HHL, 9mm SMA, BFC-HHL (8-pin), FCP (2 Pin), HHLFC, and custom package options.

### Device Specifications (Specified values are at rated power at 25° on a C-mount)

| Parameter                             | LDX-3110-735 | Units                    |
|---------------------------------------|--------------|--------------------------|
| Output Power                          | 1,750        | mW                       |
| Wavelength                            | 735          | +/-5 nm                  |
| Spectral Width                        | 1.1          | nm                       |
| Operating Temperature                 | 25           | °C                       |
| Aperture Size                         | 100          | um                       |
| Operating Current                     | 2,170        | mA                       |
| Threshold Current                     | 680          | mA                       |
| Slope Efficiency                      | 1.20         | W/A                      |
| Forward Voltage                       | 1.9          | V                        |
| Fast Axis Divergence                  | 26           | ° (FWHM)                 |
| Slow Axis Divergence                  | 6            | ° (FWHM)                 |
| Polarization                          | TM           | N/A                      |
| Fiber Size HHL, BTF, FCP <sup>1</sup> | 105 or 200   | um                       |
| Min. Fiber Size 9mm SMA <sup>2</sup>  | 250          | um                       |
| Expected Lifetime <sup>3</sup>        | >10,000      | Hours (EOL) <sup>4</sup> |

Unless otherwise indicated, all values are nominal.

1. Other fiber diameters are available upon requested.
2. If minimum fiber size is used, a high power SMA connector is required.
3. Lifetime is greatly affected by Package type, Operating temperature, Thermal resistance, Operation (CW vs Off/On), and Packaging stress
4. End of Life (EOL) is defined as when the operating current must be increased by >20% to maintain the Beginning of Life (BOL) optical output power.

LDX follows a policy of continuous product improvement.  
**Specifications are subject to change without notice.**







These components do not comply with the Federal Regulations (21 CFR Subchapter 1) as administered by the Center for Devices and Radiological health. Purchaser acknowledges that his/her products must comply with these regulations before they can be sold to a customer



**Free Space Package - Exposed Emitter**

| Package  | Features   | Options           | Drawing   |
|--|--|-------------------|---|
| C-Mount Package   | Small footprint with screw mounting<br>Material – Copper (OFHC)<br>Fast-axis lensing       | Fast-axis lensing |  |
| B-Mount Package   | Very small footprint<br>Requires soldering to heatsink<br>Material – Copper Tungsten (CuW) | Fast-axis lensing |  |
| Chip-on-Submount  | Very small footprint<br>Requires soldering to heatsink<br>Material – BeO                   | Fast-axis lensing |  |

**Free Space Package - Hermetically Sealed Windowed Packages**

| Package  | Features   | Options  | Drawing   |
|--|--|--|---|
| 9mm Package   | Industry-standard package<br>Header material – Copper                                    | Photodiode, Isolated package,<br>Fast-axis lensing |  |
| TO-3 Package  | Mounting to heatsink with screws<br>Header material – Copper                             | TEC, Thermistor, Photodiode,<br>Fast-axis lensing  |  |
| HHL Package   | Internal peltier cooler (TEC), thermistor,<br>and photodiode<br>Header material – Copper | Fast-axis lensing                                  |  |

**FAC Lensing Options:**

|                  |    |   |
|------------------|----|---|
| Best Collimation | L1 | Less than 1° divergence in the fast axis direction. |
| Squared Beam FAC | L2 | Matches the fast-axis to the slow-axis divergence.  |

**Fiber Coupled Packages - Hermetically Sealed - >80% Coupling Efficiency**

| Package  | Features   | Options                      | Drawing   |
|--|--|------------------------------|---|
| 9mm SMA FC Package  | Industry-standard package<br>SMA connector for detachable fiber<br>Header material – Copper                                  | Photodiode, Isolated package |  |
| 8-Pin BFC Package   | Built-in internal TEC and Photodiode<br>Fiber pigtail with SMA connector<br>Header material – Copper                         | Thermistor                   |  |
| 2-Pin FCP Package   | Fiber pigtail with SMA connector<br>Header material – Copper   | none                         |  |
| HHL-FC Package      | Fiber pigtail with SMA connector<br>Internal peltier cooler (TEC), thermistor,<br>and photodiode<br>Header material – Copper | none                         |  |

**Part Numbering System**

| Part Number          | Description   |
|----------------------|---|
| LDX-3115-680-9       | Semiconductor Laser Diode, 680±3 nm, 1200mW, 150um emitter, 9mm Package   |
| LDX-2405-690-BFC-105 | Semiconductor Laser Diode, 690±3 nm, 400mW, 50um emitter, Pigtailed Fiber Coupled 8-pin BFC Package w/ >80% Output Power from Fiber, Includes 105um, 0.22NA, 1m long fiber pigtail with SMA connector |
| LDX-2410-645-B-L1    | Semiconductor Laser Diode, 645±5 nm, 400mW, 100um emitter, B-mount w/ FAC Lensing, Best Collimation   |
| LDX-2710-660-HHL-L2  | Semiconductor Laser Diode, 660±3 nm, 750mW, 100um emitter, HHL Package w/ TEC, PD, Thermistor, FAC Lens, Squared Beam   |

**LDX-XXXX-XXX-XXX-XXX**

- LDX Optronics
- Chip Design
- Wavelength

**Package Type**

- C – C-Mount
- B – B-Mount
- Q – Q-Mount
- COS – Chip on Submount
- 9 – 9mm Package
- TO3 – TO-3 Package
- HHL – HHL Package
- 9-SMA – 9mm SMA Package
- HHL-FC – HHL Package
- BFC – 8 pin High Heat Load
- FCP – 2-pin Package
- CHIP – Unmounted Chip
- BAR – Unmounted Bar

**Options**

- TEC – Internal TEC
- PD – Photodiode
- T – Thermistor
- L1 - FAC Lens, Best Collimation
- L2 - FAC Lens, Squared Beam
- AR – Low AR Coating

For all handling and mounting precautions, see the [LDX Catalog](#)